

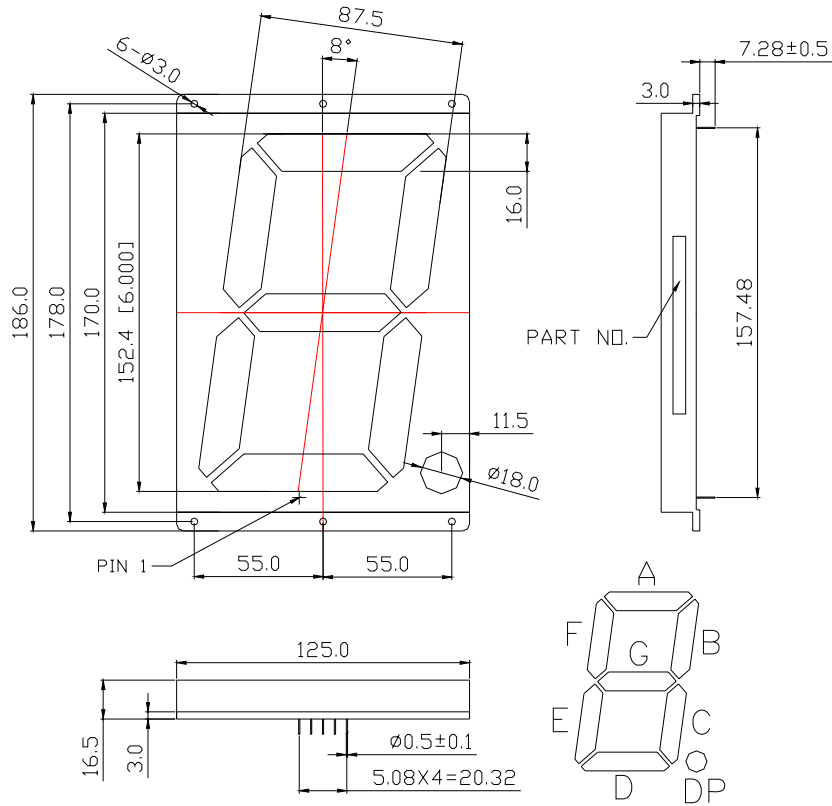
WCN1-00F0SD-A23**SPECIFICATION**

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei	Athena		



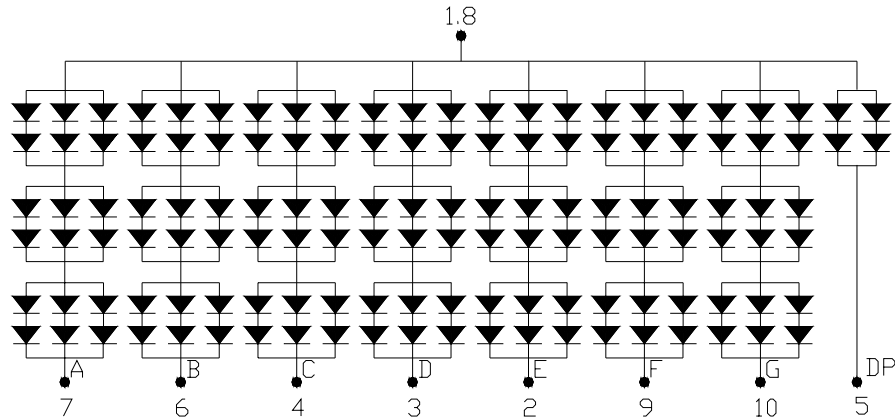
REVISION: A1

Outer Dimension:



Notes: Unless otherwise stated, The tolerance is $\pm 0.25\text{mm}$.

Circuit Diagram:



Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Common Anode	6	Cathode B
2	Cathode E	7	Cathode A
3	Cathode D	8	Common Anode
4	Cathode C	9	Cathode F
5	Cathode DP	10	Cathode G

WCN Opto Group Co., Limited

■ Features:

- High Reliability
- Color: Super Red
- Low Power Requirement
- Easy Assembly

■ Description:

- Single Digit LED Display
- Digit Height: 152.4 mm (6.0")
- Black Face and milky Segment

■ Absolute Maximum Rating (Ta=25°C):

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Segment/DP	P _d	—	Red	800/170	mW
Forward Current Per Segment/DP	I _F	—	Red	60/40	mA
Peak Forward Current Per Segment	I _{FP}	1/10 Duty 10KHz	Red	100	mA
Reverse Voltage Per Segment/DP	V _R	—	Red	30/10	V
Operating Temperature Range	Topr	—	—	-35~+85	°C
Storage Temperature Range	Tstg	—	—	-35~+85	°C

■ Electrical/Optical Characteristics Rating(Ta=25°C)

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =60mA	Per Segment	—	12.00	15.60	V
		I _F =40mA	DP		4.00	5.20	
Reverse Current	I _R	V _R =30V	Per Segment	—	—	100	μA
		V _R =10V	DP				
Luminous Intensity	I _V	I _F =30mA	Per Segment	31001	43000	—	ucd
Wave Length	λ _P	I _F =60mA	Per Segment	—	660	—	nm
	λ _D				640		
Spectral Line Half Width	△λ	I _F =60mA	Per Segment	—	20	—	nm
Luminous Intensity Matching Ratio (Segment to Segment)	I _{v-m}	I _F =30mA	—	—	—	1.3:1	

■ Luminous Intensity Sorting: (Luminous Intensity Tolerance is +/-10%)

Rank	Symbol	Condition	Min	Max	Unit
W	W	I _F =10mA	31001	37000	ucd
X	X	I _F =10mA	37001	43000	ucd
Y	Y	I _F =10mA	43001	50000	ucd
Z	Z	I _F =10mA	50001	58000	ucd

■ Soldering Conditions: Soldering Temp. ≤+260°C

Soldering Time. ≤3sec. (at 2mm Distance from The Case of Reflector Edge)

■ **Typical Electro-Optical Characteristics Curve:**

Fig1. Forward Current vs. Forward Voltage:

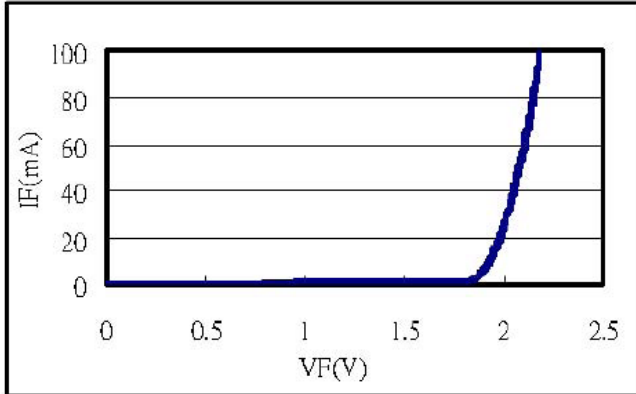


Fig2. Forward Current vs. Relative Intensity:

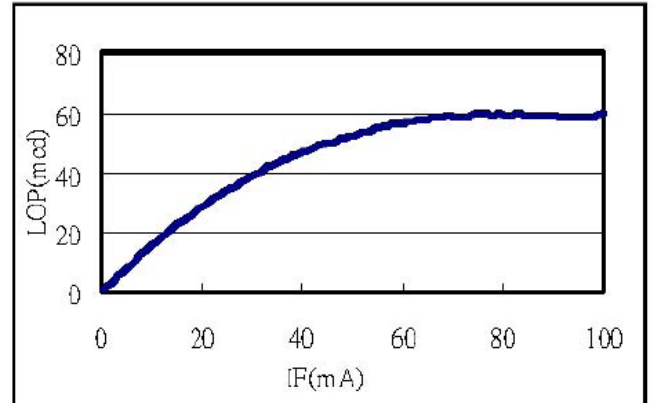


Fig3. Forward Current vs. Relative Wavelength:

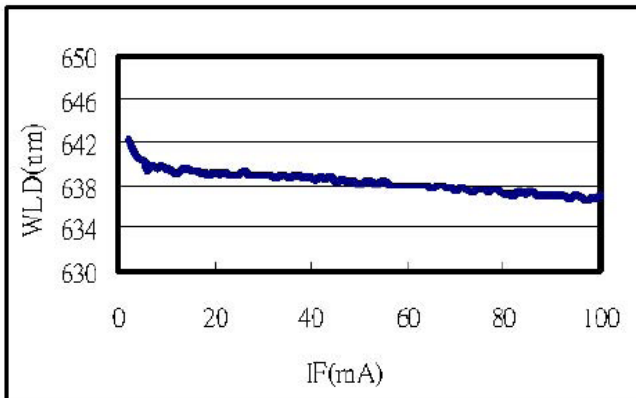


Fig4. Temperature vs. Relative Intensity:

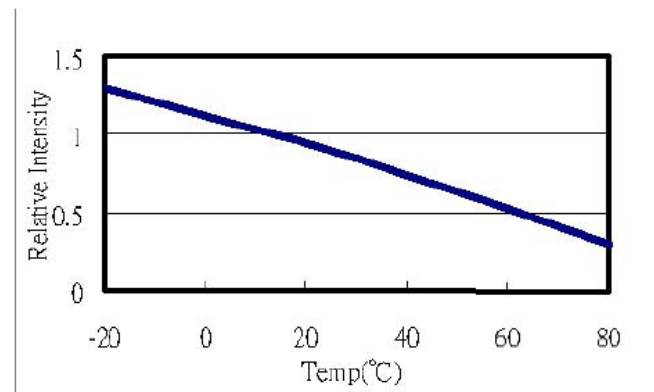


Fig5. Temperature vs. Relative Wavelength:

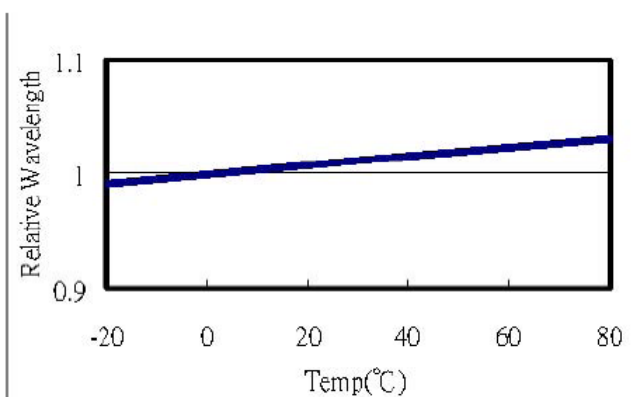
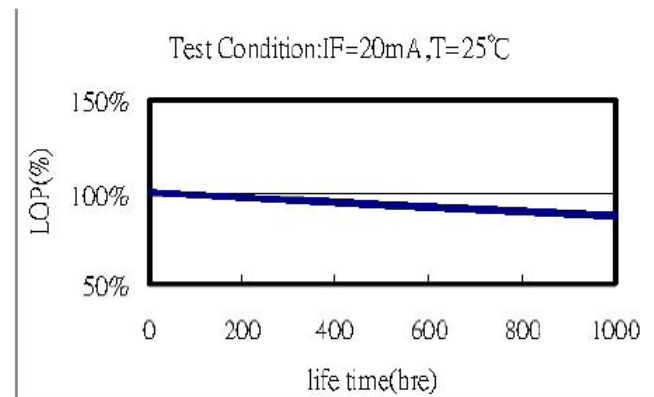


Fig6. Life Test at 20mA R.T. 1000hrs:



LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T _a = UNDER ROOM TEMPERATURE I _F = I _F max
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY T _a = 65±5°C RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE T _a = 85±5°C(COB: T _a =65±5°C) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE T _a = -35±5°C TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION 85°C ~ 25°C ~ -35°C ~ 25°C 30min 5min 30min 5min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES 85±5°C ~ -35±5°C 10min 10min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE T.SOL=230±5°C DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING T.SOL=260±5°C DWELL TIME=10±1sec.

Packing method A:

3pcs / Red Expandable Polyethylene.

21pcs / Box(360*265*255mm).

42 pcs / Carton(550*380*280mm).